

## 1. General description

Ultrafast power diode in a SOD1113 (2-lead TO-220F) plastic package.

## 2. Features and benefits

- Fast switching
- Isolated plastic package
- Low leakage current
- Low forward voltage drop
- Low thermal resistance
- Soft recovery characteristic

## 3. Applications

- High frequency switched-mode power supplies
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

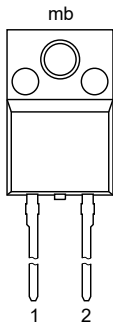
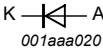
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V <sub>R</sub>	reverse voltage	DC		-	-	600	V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; T <sub>h</sub> ≤ 71 °C; square-wave pulse; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	-	10	A
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse; <a href="#">Fig. 4</a>		-	-	80	A
		t <sub>p</sub> = 8.3 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse		-	-	88	A
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.5	2	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 6</a>		-	-	1.6	V
Dynamic characteristics							
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	35	50	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-220F (SOD113)</p>	
2	A	anode		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

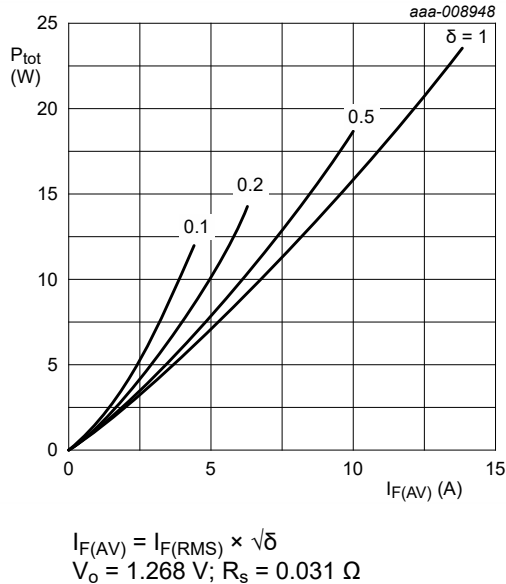
Type number	Package		
	Name	Description	Version
BYV10X-600P	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220 "full pack"	SOD113

## 7. Limiting values

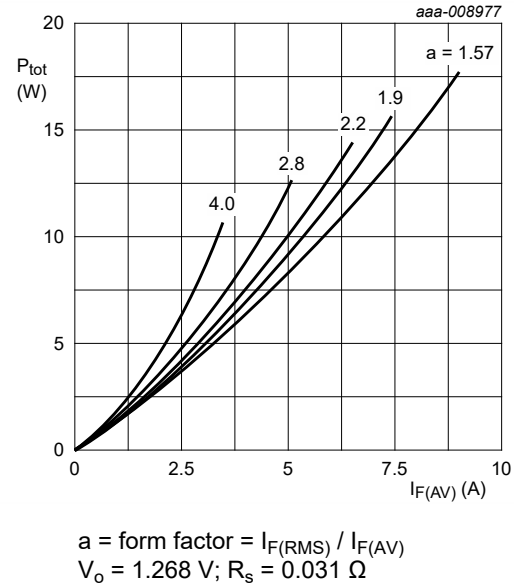
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	DC	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_h \leq 71^\circ\text{C}$ ; square-wave pulse; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	10	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_h \leq 71^\circ\text{C}$ ; square-wave pulse	-	20	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\ \text{ms}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	-	80	A
		$t_p = 8.3\ \text{ms}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; sine-wave pulse	-	88	A
$T_{\text{stg}}$	storage temperature		-65	175	$^\circ\text{C}$
$T_j$	junction temperature		-	175	$^\circ\text{C}$



**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



**Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

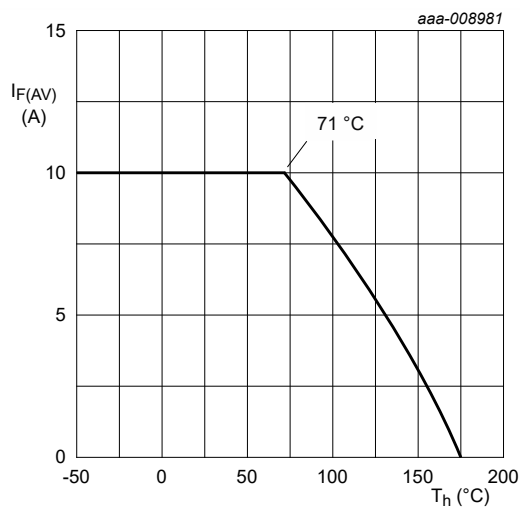


Fig. 3. Forward current as a function of heatsink temperature; maximum values

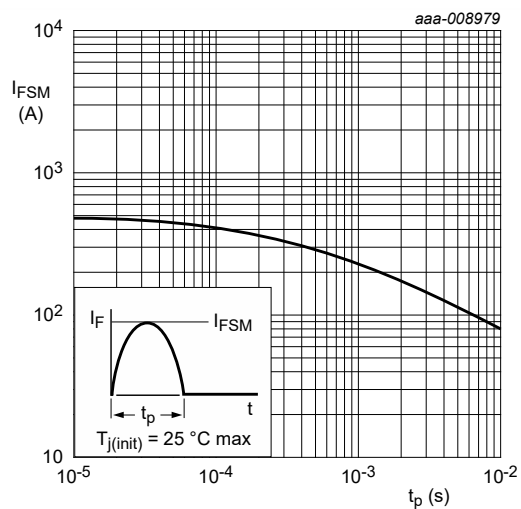
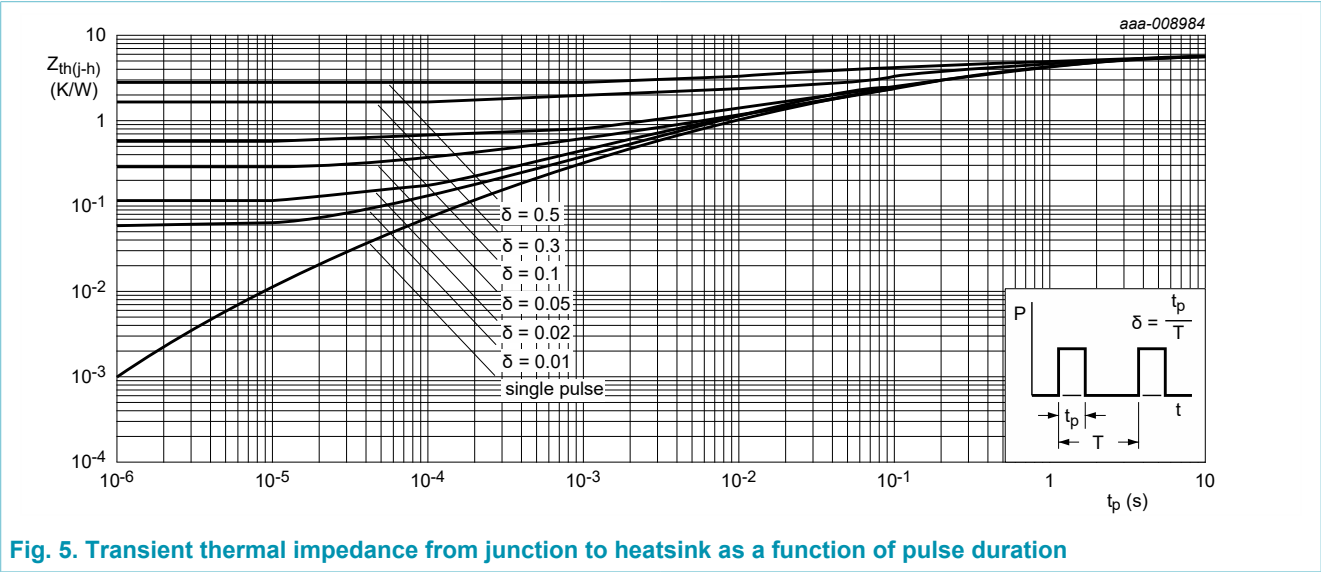


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-h)</sub>	thermal resistance from junction to heatsink	without heatsink compound	-	-	7.2	K/W
		with heatsink compound; Fig. 5	-	-	5.5	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W



9. Isolation characteristics

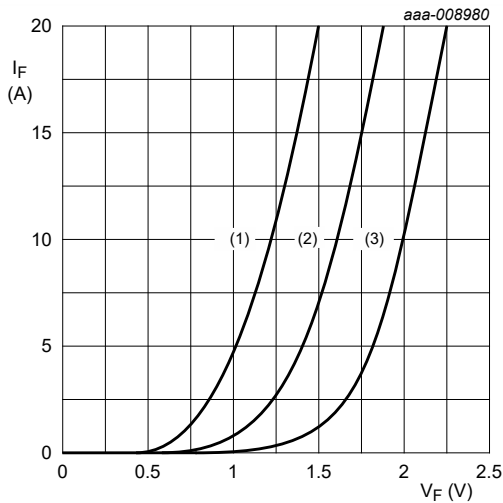
Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>isol(RMS)</sub>	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C <sub>isol</sub>	isolation capacitance	from cathode to external heatsink	-	10	-	pF

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.5	2	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 6</a>		-	-	1.6	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	-	10	μA
		V <sub>R</sub> = 500 V; T <sub>j</sub> = 150 °C		-	-	250	μA
Dynamic characteristics							
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	35	50	ns
		I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	20	-	ns
		I <sub>F</sub> = 10 A; V <sub>R</sub> = 200 V; dI <sub>F</sub> /dt = 200 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	40	-	ns



V<sub>0</sub> = 1.268 V; R<sub>s</sub> = 0.031 Ω  
(1) T<sub>j</sub> = 150 °C; typical values  
(2) T<sub>j</sub> = 150 °C; maximum values  
(3) T<sub>j</sub> = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage

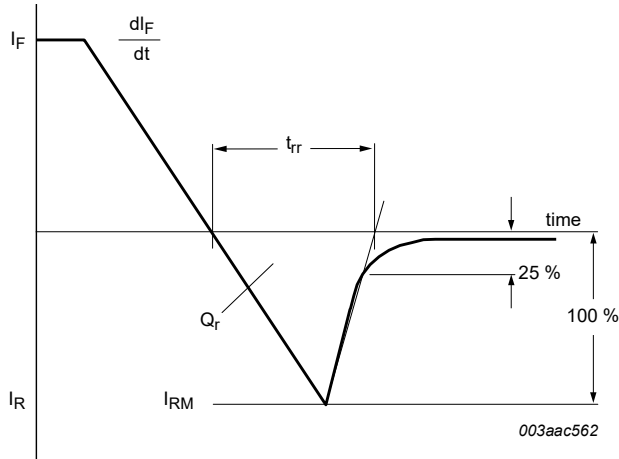


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline

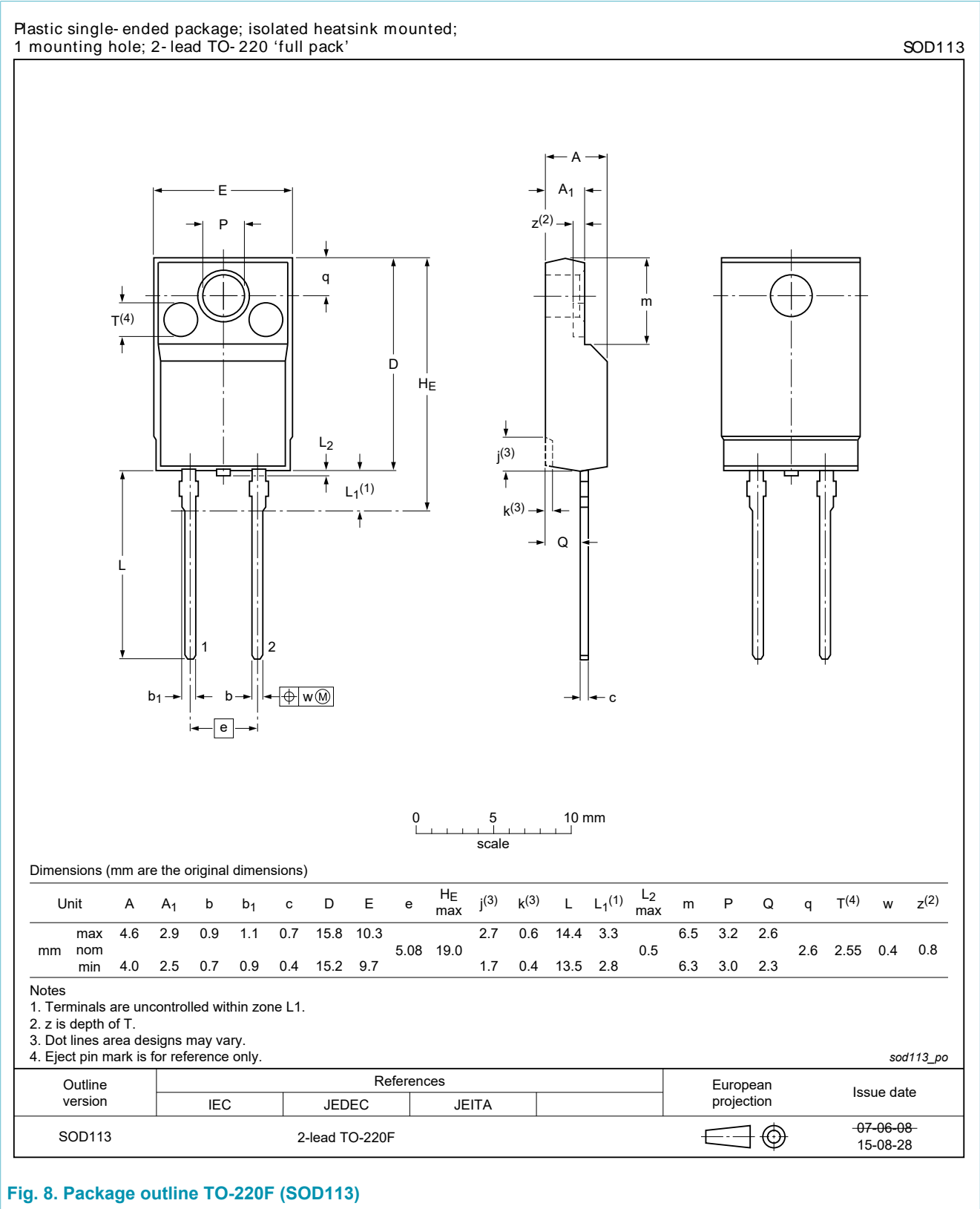


Fig. 8. Package outline TO-220F (SOD113)

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Date of release: 26 September 2018